

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Sung-Duck CHUN</td> <td>05/20/2008</td> </tr> <tr> <td>Young-Dae LEE</td> <td>05/20/2008</td> </tr> <tr> <td>Myung-Cheul JUNG</td> <td>05/20/2008</td> </tr> <tr> <td>Sung-Jun PARK</td> <td>05/20/2008</td> </tr> </tbody> </table>		Name	Execution Date	Sung-Duck CHUN	05/20/2008	Young-Dae LEE	05/20/2008	Myung-Cheul JUNG	05/20/2008	Sung-Jun PARK	05/20/2008
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<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>LG Electronics, Inc.</td> </tr> <tr> <td>Street Address:</td> <td>20, Yoido-dong, Yongdungpo-gu</td> </tr> <tr> <td>City:</td> <td>Seoul</td> </tr> <tr> <td>State/Country:</td> <td>REPUBLIC OF KOREA</td> </tr> </table>		Name:	LG Electronics, Inc.	Street Address:	20, Yoido-dong, Yongdungpo-gu	City:	Seoul	State/Country:	REPUBLIC OF KOREA		
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CORRESPONDENCE DATA											
<p>Fax Number: (213)623-2211 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 213-623-2221 Email: patent@lhlaw.com Correspondent Name: Lee,Hong,Degerman,Kang & Waimey Address Line 1: 660 S. Figueroa Street Address Line 2: Suite 2300 Address Line 4: Los Angeles, CALIFORNIA 90017</p>											
ATTORNEY DOCKET NUMBER:	2101-3505										
NAME OF SUBMITTER:	Harry S. Lee										
<p>Total Attachments: 2 source=2101-3505_Assignment#page1.tif</p>											

CH \$40.00 12160095

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PATENT
REEL: 022404 FRAME: 0149

ASSIGNMENT

(1-8) *Insert Name(s) of
Inventor(s)*

(1) Sung-Duck CHUN (5)
(2) Young-Dae LEE (6)
(3) Myung-Cheul JUNG (7)
(4) Sung-Jun PARK (8)
(5)

In consideration of the sum of one dollar (\$1.00) and other good and valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to

(9) *Insert name of Assignee*

(9) LG ELECTRONICS INC.

(10) *Insert state of Incorporation
of Assignee*

(10) Republic of Korea

(11) *Insert address of Assignee*

(11) 20, Yoido-Dong, Yongdungpo-Gu, Seoul, 150-010, Korea

(hereinafter designated as the Assignee) the entire worldwide right, title and interest in the invention known as

(12) *Insert identification of
Invention, such as Title,
Case Number or Foreign
Application Number*

**(12) ALLOCATING RADIO RESOURCES IN MOBILE COMMUNICATIONS
SYSTEM**

for which the undersigned has (have) executed an application for patent in the United States of America and all patent applications in foreign countries corresponding thereto or based thereon.

(13) *Insert Date of Signing of
Application*

(13) May 20, 2008

1) The undersigned agree(s) to execute all papers necessary in connection with any original, reissue, divisional and continuing United States and foreign applications for the above-identified invention and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

2) The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation or division thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

3) The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

4) The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

5) The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed any agreement in conflict herewith.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed any agreement in conflict herewith.

Attorney Docket No.:

The undersigned hereby appoints the **ATTORNEYS ASSOCIATED WITH CUSTOMER NO. 035884** the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Date: May 20, 2008 Signature of Inventor JK
Date: May 20, 2008 Signature of Inventor CS
Date: May 20 2008 Signature of Inventor T.P. MC
Date: May 20, 2008 Signature of Inventor Wle
Date: _____ Signature of Inventor _____